



Technical Data Sheet

High Power Infrared LED

Features

- Small package with high efficiency
- Peak wavelength $\lambda_p=850\text{nm}$
- Soldering methods: SMT
- Thermal resistance (junction to lead): $35^\circ\text{C}/\text{W}$.
- Pb free
- The product itself will remain within RoHS compliant version.

HIR-A07/L183-P01



Descriptions

- HIR-A07/L183-P01 series is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- The device is spectrally matched with silicon photodiode, Phototransistor.

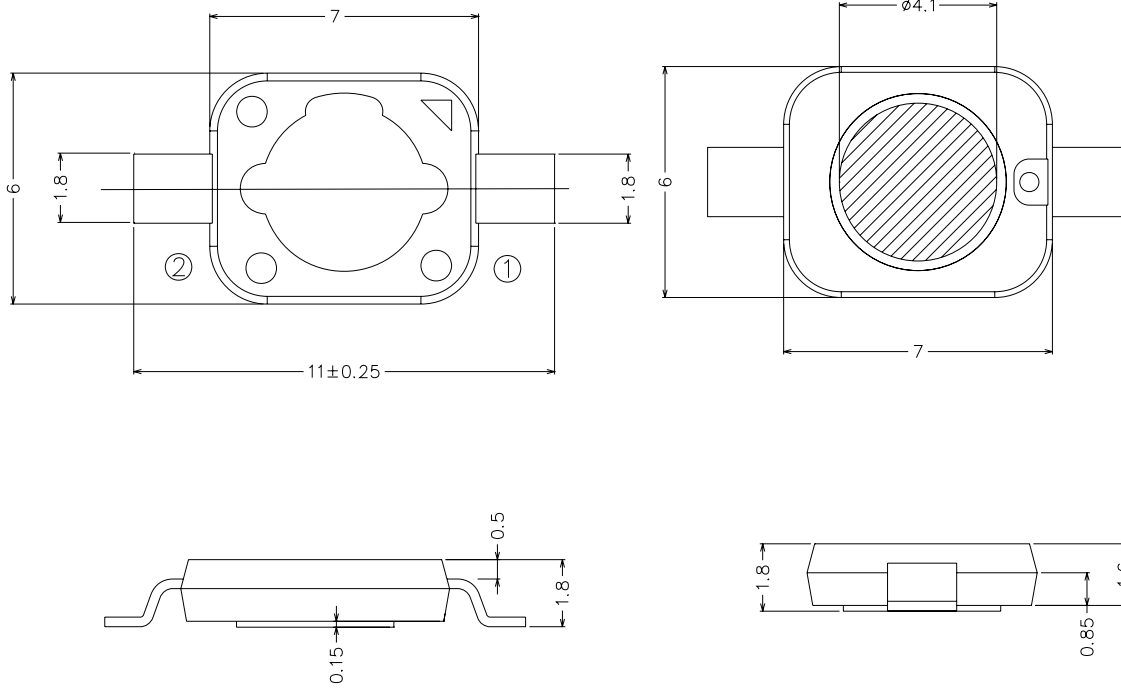
Applications

- CCD Camera
- Night Vision
- Infrared applied system

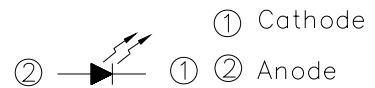
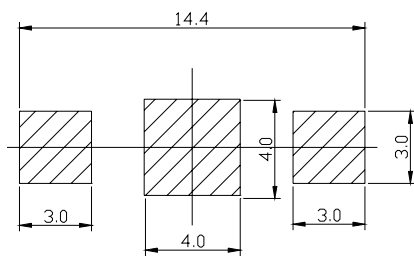
Materials

Items	Description
Housing	Heat resistant polymer
Encapsulating Resin	Clear silicone resin
Electrodes	Ag plating copper alloy
Die attach	Silver paste
Chip	AlGaAs

Package Dimensions



Recommended solder pad



- Notes:**
1. All dimensions are in millimeters
 2. Tolerances unless dimensions ± 0.25 mm

HIR-A07/L183-P01

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Forward Current	I_F	700	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	°C
Junction temperature	T_j	125	°C
Power Dissipation @ $I_F=700mA$	P_d	1	W

Note: We suggest that customer should add the heat sink with

HIR-A07/L183-P01

to exclude the heat.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Total Radiated Power	P_o	$I_F=350mA$	60	110	--	mW
		$I_F=700mA$	120	220	--	
Radiant Intensity	I_E	$I_F=350mA$	10	35	--	mW/sr
		$I_F=700mA$	30	70	--	
Peak Wavelength	λ_p	$I_F=20mA$	--	850	--	nm
Spectral Bandwidth	$\Delta \lambda$	$I_F=20mA$	--	50	--	nm
Forward Voltage	V_F	$I_F=350mA$	1.0	1.6	2.5	V
		$I_F=700mA$	1.2	1.9	3.0	
Reverse Current	I_R	$V_R=5V$	--	--	10	μA
Optical Rise Time	T_r	$I_F=20mA$	--	11	--	ns
Optical Fall Time	T_f	$I_F=20mA$	--	7	--	ns
View Angle	$2\theta_{1/2}$	$I_F=20mA$	--	125	--	deg
Thermal resistance, junction to heat-sink	$R_{th\ j-L}$	$I_F=700mA$	--	35	--	°C/W

Note. 1. Radiometric measurement tolerance : $\pm 10\%$

2. $2\theta_{1/2}$ is the off axis angle from lamp centerline where the radiant intensity is 1/2 of the peak value.

3. Forward Voltage measurement tolerance : $\pm 0.1V$

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

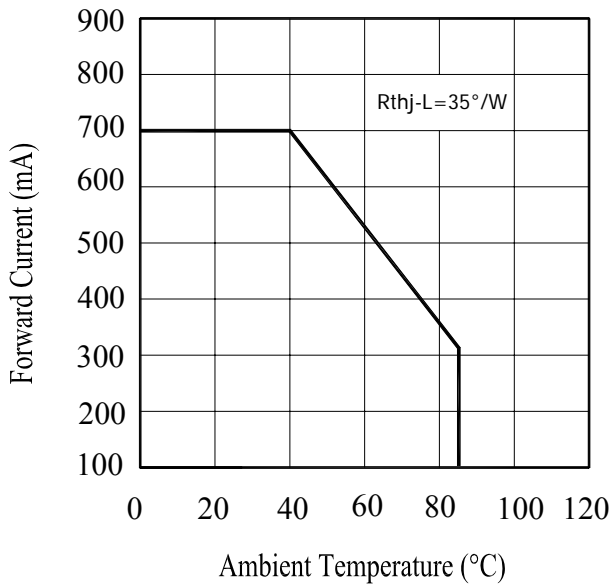


Fig.2 Spectral Distribution

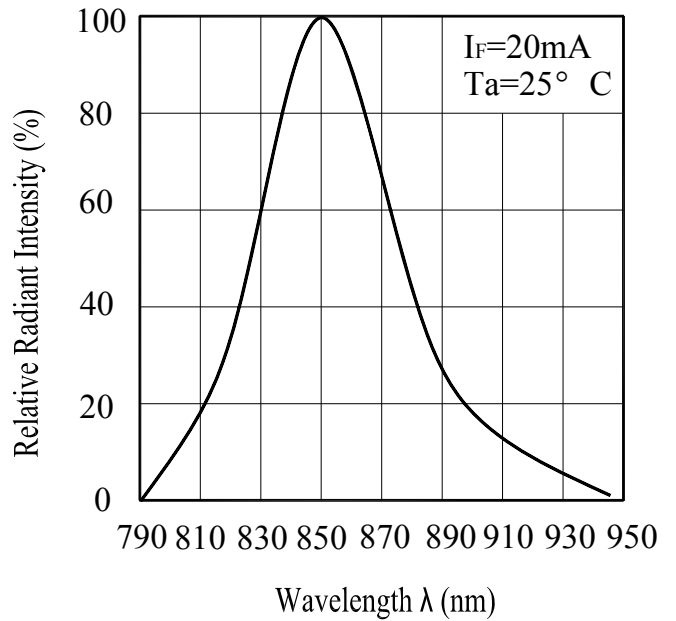


Fig.3 Peak Emission Wavelength vs. Ambient Temperature

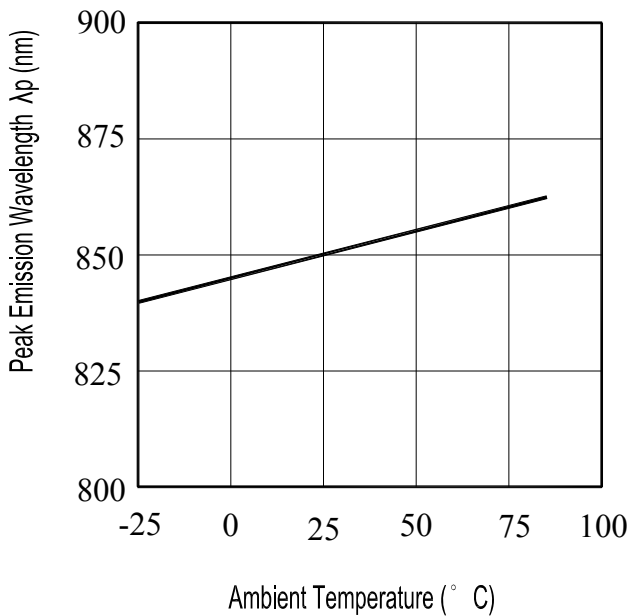
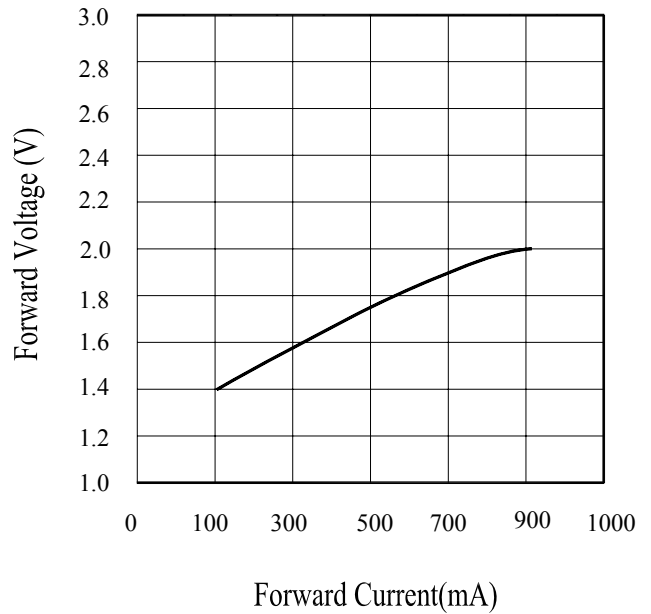
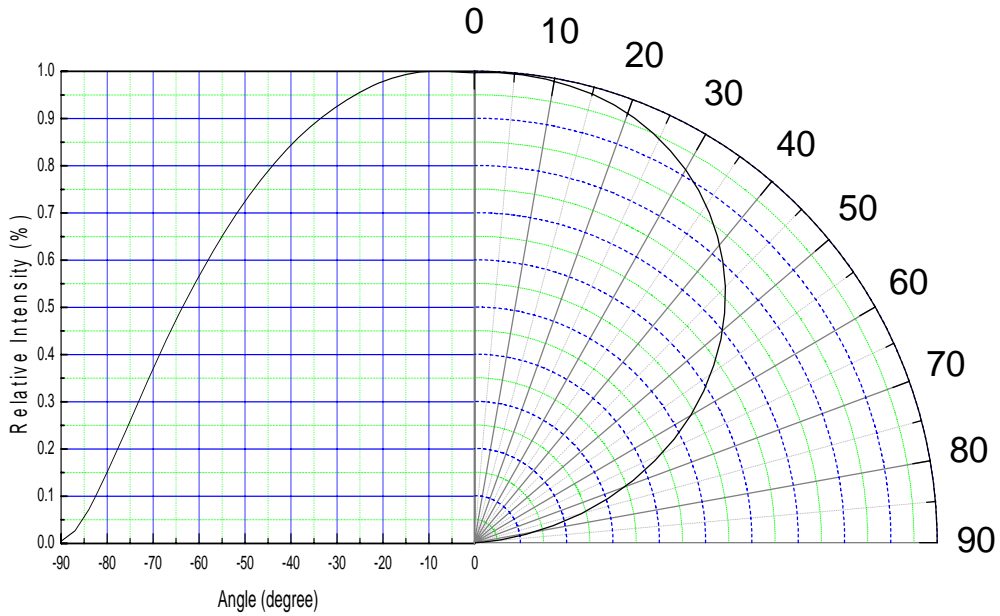


Fig.4 Forward Current vs. Forward Voltage



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs. Angular Displacement



Precautions For Use

1.Over-current-proof

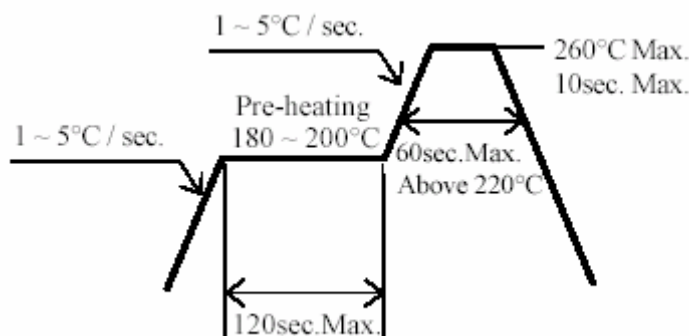
Though HIR-A07/L183-P01 has conducted ESD protection mechanism, customer must not use the device in reverse and should apply resistors for extra protection. Otherwise slight voltage shift may cause enormous current change and burn out failure would happen.

2.Thermal Management

- i. Because HIR-A07/L183-P01 is a high power dissipation device, special and sufficient consideration in thermal management design must be made to optimize the thermal performance.
- ii. Heat sink design is implemented in the device for an additional thermal connection. Since the device is capable of SMT process, tin must be spread both heat sink and solder pads areas to dissipate the heat.
- iii. A high thermal conductivity substrate, such as Aluminum or Copper plate etc, must be applied for external thermal management. It is strongly recommended that the outer heat sink or PCB dimension per LED can not be less than 25 x 25 x 1 (L x W x H) mm. The materials for outer heat sink can be FR4 on Aluminum, MCPCB, or FPC on Aluminum.
- iv. Special thermal designs are also recommended to take in outer heat sink design, such as FR4 PCB on Aluminum with thermal vias or FPC on Aluminum with thermal conductive adhesive, etc.
- v. Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and LED lifetime will decrease critically.

3.Soldering Condition

1.Lead reflow soldering temperature profile



2.Reflow soldering should not be done more than two times.

3.While soldering, do not put stress on the LEDs during heating.

4.After soldering, do not warp the circuit board

4.Soldering Iron

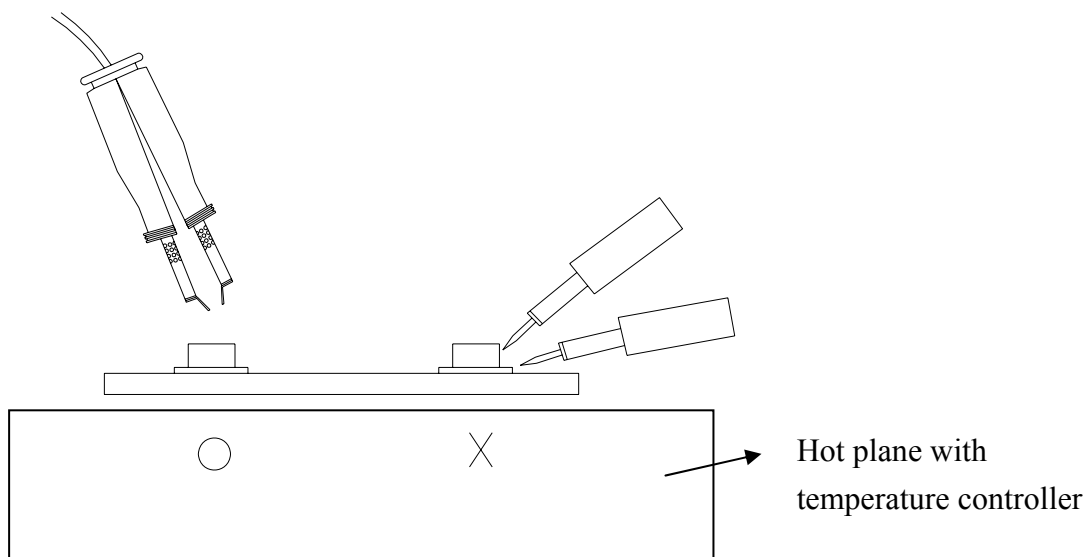
- 1.For prototype builds or small series production runs it is possible to place and solder the LED by hand.
- 2.Dispensing thermal conductive glue or grease on the substrates and follow its curing spec. Press LED housing to closely connect LED and substrate.
- 3.It is recommended to hand solder the leads with a solder tip temperature of 280°C for less than 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal.
- 4.Be careful because the damage of the product is often started at the time of the hand solder.

5.Handling Indications

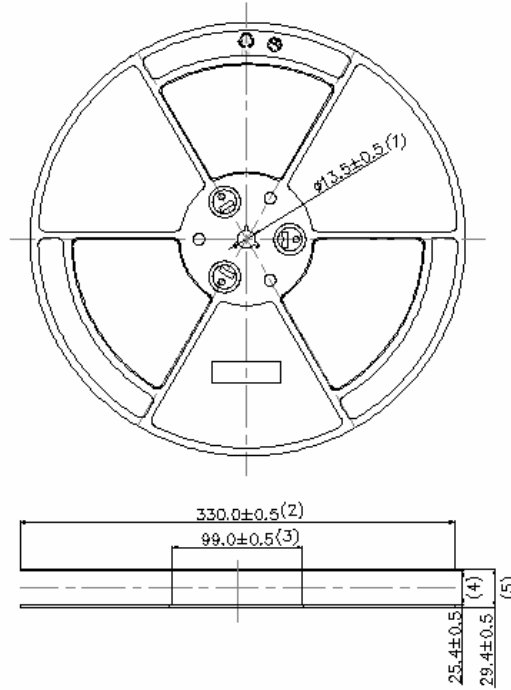
During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.

6.Repairing

Repair should not be done after the LEDs have been soldered. If unfortunately, repair is unavoidable. In addition to double-head soldering iron, hot plane must be used under external heat sink plate to liquefy tin between device heat sink and outer heat sink, shown as figure below. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

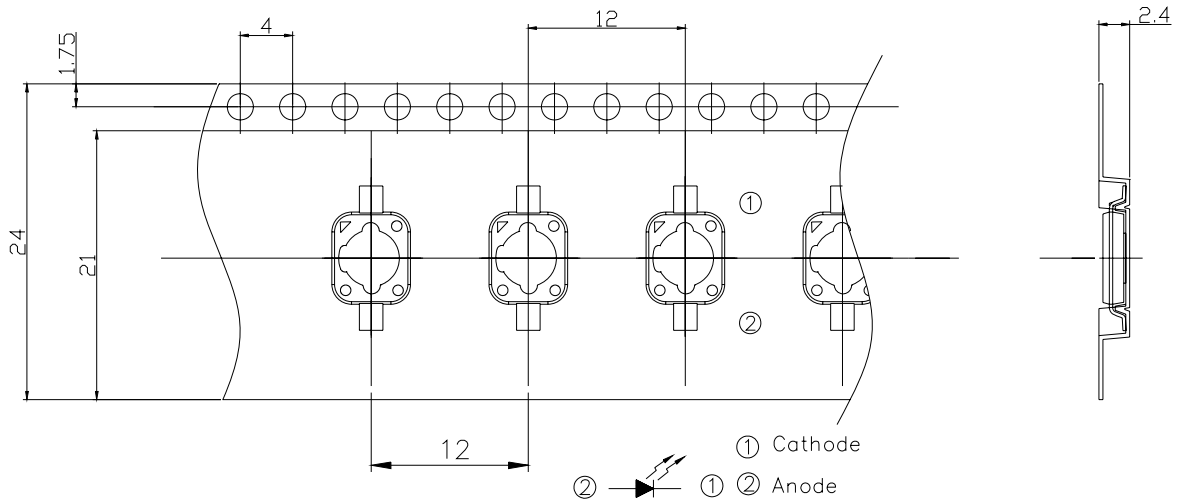


Tube Packing Specifications
1.Reel Dimensions



- Note: 1. Dimensions are in millimeters**
- 2. The tolerances unless mentioned is ± 0.1 mm**

2.Carrier Tape Dimensions: Loaded quantity 800 PCS per reel.



- Note: 1. Dimensions are in millimeters**
- 2. The tolerances unless mentioned is ± 0.1 mm**

Reliability Test Item And Condition

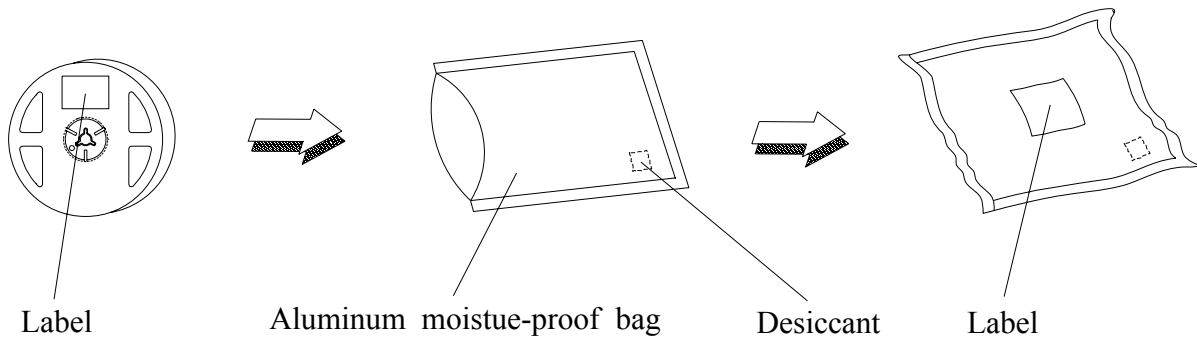
The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

NO.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgement Criteria	Ac/Re
1	REFLOW Soldering	TEMP. : 260°C±5°C 10secs	6Mins	22pcs	$I_R \geq U \times 2$	0/1
2	Temperature Cycle	H : +100°C 15mins ↑ 5mins ↓ 15mins L : -40°C	300Cycles	22pcs	$I_e \leq L \times 0.8$ $V_F \geq U \times 1.2$	0/1
3	Thermal Shock	H : +100°C 5mins ↑ 10secs ↓ 5mins L : -10°C	300Cycles	22pcs	U : Upper Specification Limit	0/1
4	High Temperature Storage	TEMP. : +100°C	1000hrs	22pcs	L : Lower Specification Limit	0/1
5	Low Temperature Storage	TEMP. : -40°C	1000hrs	22pcs		0/1
6	DC Operating Life	$I_F = 700\text{mA}$	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85°C / 85% R.H	1000hrs	22pcs		0/1

Moisture Resistant Packaging



Label Form Specification



CPN: Customer's Production Number
 P/N : Production Number
 QTY: Packing Quantity
 CAT: Ranks
 HUE: Peak Wavelength
 REF: Reference
 LOT No: Lot Number
 MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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